Micro/Nano-Electronics Packaging & Assembly, Design and Manufacturing Forum

March 10-11, 2022 – Grenoble, France

Call for extended abstracts

Extended Abstracts (2 pages typical, including graphs, pictures, …) are requested on the following topics :

Advanced packaging :
TSVs, 2,5 & 3D interposers, wafer level packaging, embedded IC packages, SiP, PoP, MEMS packaging, power packaging, advanced substrates, PCB, Fan Out wafer and panel level processes.

Assembly and manufacturing technologies:
Bonding, advanced dicing, flux, cleaning, dispensing, coating technologies, materials & equipment related to assembly manufacturing and business aspects of the industry.

Advanced interconnections:
Flip-chip including ultra-fine pitches approaches, interconnections, IMC studies, bumping techniques (solder bumps, Cu pillars,...) disruptive interconnections, optical connections.

Emerging & sustainable technologies & applications:
Flexible/stretchable packaging, nanomaterial for interconnections, green/bio and sustainable technologies for packaging, additive manufacturing, Nano manufacturing.

Innovative Materials equipment's and processes:
3D materials, conductive & non-conductive adhesives, underfill, molding, disruptive solder alloys, thermal interface. Innovative equipment for assembly & packaging.

Reliability & tests:
Applied reliability for LED, Displays, IoT, MEMS, memories, medical devices, autonomous vehicles. Life models, failure analysis techniques & characterizations.

Imaging & photonics assembly technologies:
Assembly & packaging technologies for optical and photonics applications : imaging, displays, silicon photonics, optical sensors, high energy physics and medical imaging.

Thermal/mechanical simulation and characterization:
Components, boards & system level modelling for : interconnections, interposers, substrates, WLP & embedded packages, power modules, optical packaging, RF and MEMS.

Practical information

Organization :

IMAPS France
Email: imaps.france@orange.fr
Web: www.france.imapseurope.org

General chair: Alexandre VAL (VALEO)
Technical Chairs:
Sanae BOULAY (ASML),
Jean-Luc DIOT (Assemblinnov),
Michel GARNIER (ST Microelectronics),
Romain COFFY (ST Microelectronics),
Jean-Charles SOURIAU (CEA-LETI),
Christophe ZINCK (ASE),
Gilles SIMON (CEA-LETI).

Location : Close to Grenoble Railway Station

WTC / Congress center

5 -7 , place Robert Schuman – BP 1521

38025 Grenoble Cedex 1

FRANCE

Exhibition area :

Equipment & Product suppliers in the WTC Atrium during the workshop

Important dates

Extended abstracts submission date :

From **May 6th , 2021** to ~~**November 28th , 2021**~~

Extended to 15th December 2021

Your submission must include the mailing address, business phone number and email address and the content must be without commercial information**.**

Address your abstract to :

imaps.france@orange.fr

Notification of acceptance :

Authors will be notified of paper acceptance with instructions for presentation **before December 28th, 2021.**

Presentations :

Presentation should be ready one day before the workshop and supply to the chairwomen or chairmen of your session.

Social event :

Evening dinner & visit on the 10th of March 2022

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